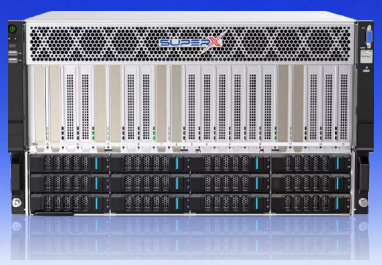
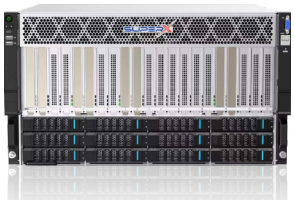
XI6150



10-GPUs

BUILT FOR THE AGE OF AI INFERENCE

Key Features



Multi-Engine Compute Architecture

- Heterogeneous computing power designed to support a wide range of AI accelerators
- Unified platform for training and inference, meeting diverse AI workload requirements with flexibility and efficiency

Flexible Topology

- Five GPU topology configurations to adapt to different application scenarios
- Intelligent resource orchestration ensures optimal utilization and high-efficiency compute performance

Advanced GPU Support

- Compatible with next-generation, high-performance GPUs
- Supports up to 10 dual-slot GPUs, 8 triple-slot GPUs, or 8 quad-slot GPUs
- Up to 600W power delivery per GPU, enabling maximum performance for demanding AI workloads

Target Workloads

- LLM Computing Infrastructure
- Enterprise AI Service Engine
- Digital Twin Rendering Hub
- Scientific HPC Platform
- 8K Media Acceleration Core

Specification

Dimensions	6U (W447 x H263.7x D926.9MM)
Motherboard	BM-X13DEPS3
CPU	Intel® Xeon® 4th-or 5th-Generation Scalable Processors
Chipset	System on Chip
Memory	8-Channel DDR5 RDIMM/MRDIMM, 32 x DIMMS
LAN	1*OCP3.0 network card 1/10/25/50/100/200/400GE PCIe Network
Video	Integrated in ASPEED® AST2600-1 x VGA port
Storage	Front hot-swap: 12 x 3.5" SATA 2*2280/22110 SATA M.2 or 1*2280/22110 NVMe M.2 SSD
GPU	10 dual-wide cards, 8 triple-wide cards, or 8 quad-wide card
PCIe Expansion Slots	PCIe Gen5 x 16*10
I/O Ports	Front: 2 x USB 3.0 1 x VGA 1 x Type-C 1 x MGMT
TPM	1 x TPM header(SPI) Optional TPM2.0
Power Supply	8 x 2700W 80 PLUS Titanium redundant power supplies AC Input: 115-240V
System Management	ASPEED® AST2600 Baseboard Management, Support PMI2.0/Redfish/SOL/KVM
System Fans	CPU Tray: 4*8056 fans GPU tray: 10*8056 fans
Operating Properties	Operating: 0°C to 35°C 5% to 95% (non-condensing)
Packaging Content	2 x CPU heatsinks 4 x Carriers 1 x L-shape Rail kit

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